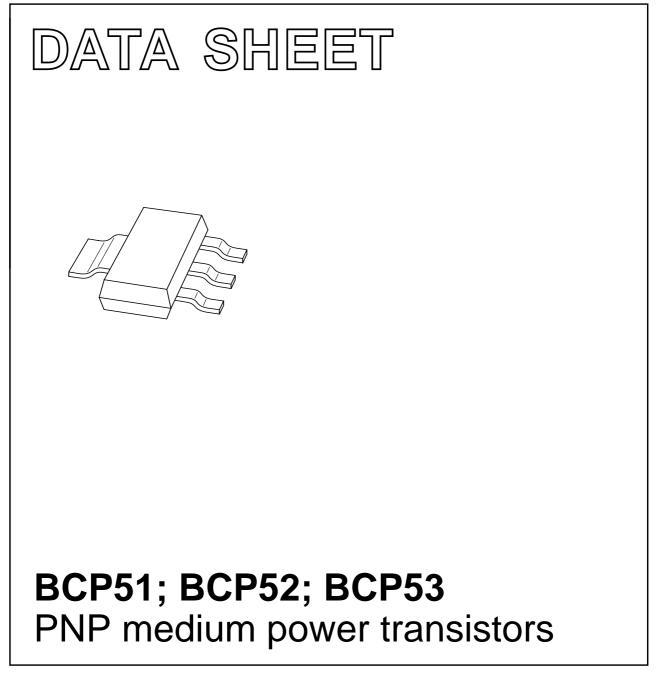
DISCRETE SEMICONDUCTORS



Product specification Supersedes data of 2001 Oct 10 2003 Feb 06



FEATURES

- High collector current
- 1.3 W power dissipation.

APPLICATIONS

- General purpose medium power DC applications
- Low and medium frequency AC applications
- Peripheral drivers
- Linear voltage regulators and battery chargers.

DESCRIPTION

PNP medium power transistor in a SOT223 plastic package. NPN complements: BCP54, BCP55 and BCP56.

BCP51; BCP52; BCP53

PINNING

PIN	DESCRIPTION	
1	base	
2, 4	collector	
3	emitter	

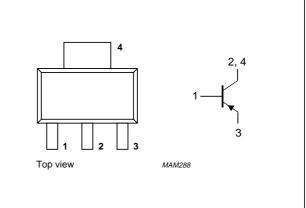


Fig.1 Simplified outline (SOT223) and symbol.

QUICK REFERENCE DATA

SYMBOL	PARAMETER		UNIT
V _{CEO}	collector-emitter voltage	-80	V
I _C	collector current (DC)	-1	А
I _{CM}	peak collector current	–1.5	A

BCP51; BCP52; BCP53

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter			
	BCP51		_	-45	V
	BCP52		_	-60	V
	BCP53		_	-100	V
V _{CEO}	collector-emitter voltage	open base			
	BCP51		_	-45	V
	BCP52		_	-60	V
	BCP53		-	-80	V
V _{EBO}	emitter-base voltage	open collector	_	-5	V
I _C	collector current (DC)		-	-1	А
I _{CM}	peak collector current		-	-1.5	А
I _{BM}	peak base current		-	-0.2	A
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; note 1	-	1.3	W
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature – 150		150	°C	
T _{amb}	operating ambient temperature -65 +150				°C

Note

1. Device mounted on a printed-circuit board, single-sided copper, tinplated, mounting pad for collector 1 cm². For other mounting conditions, see *"Thermal considerations for SOT223 in the General Part of associated Handbook"*.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-a}	thermal resistance from junction to ambient	note 1	95	K/W
R _{th j-s}	thermal resistance from junction to soldering point		14	K/W

Note

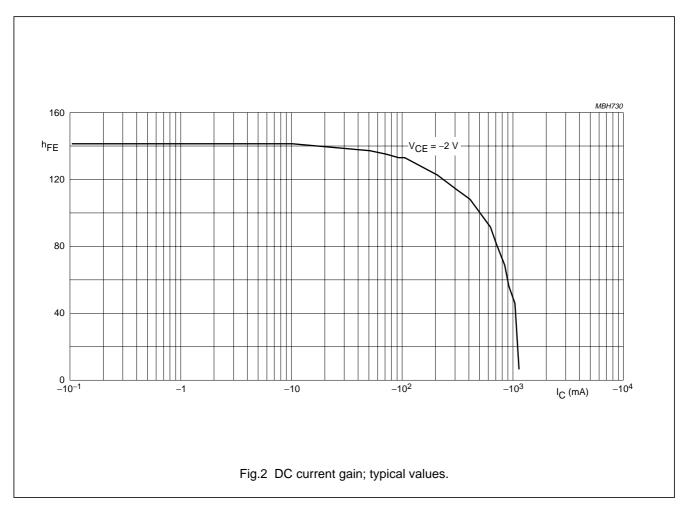
1. Device mounted on a printed-circuit board, single-sided copper, tinplated, mounting pad for collector 1 cm². For other mounting conditions, see *"Thermal considerations for SOT223 in the General Part of associated Handbook"*.

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CHARACTERISTICS

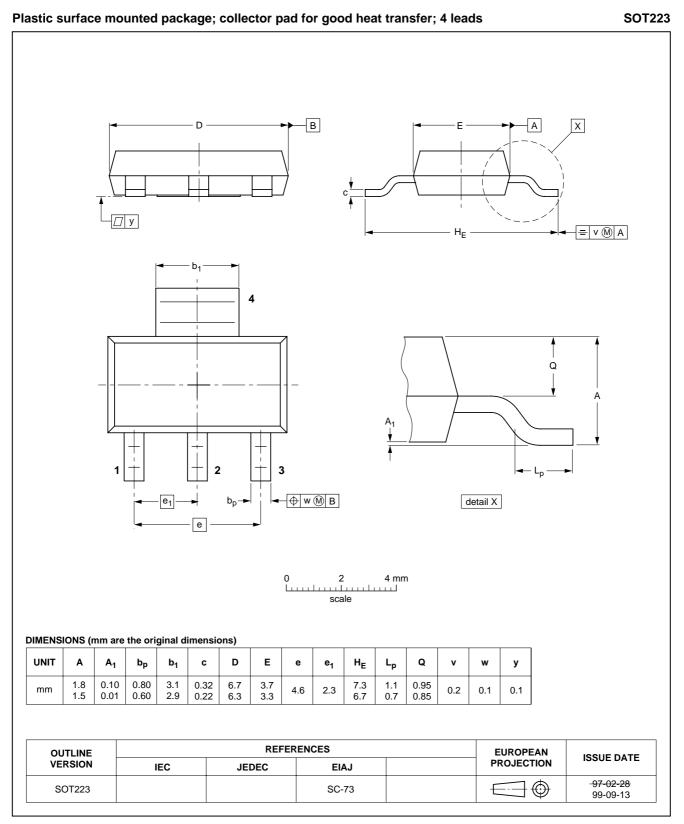
 T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER CONDITIONS		MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector cut-off current	$I_E = 0; V_{CB} = -30 \text{ V}$	_	-	-100	nA
		I _E = 0; V _{CB} = -30 V; T _j = 125 °C	_	-	-10	μΑ
I _{EBO}	emitter cut-off current	$I_{C} = 0; V_{EB} = -5 V$	_	_	-100	nA
h _{FE}	DC current gain	$V_{CE} = -2 V$; see Fig.2				
		I _C = -5 mA	63	-	-	
		I _C = -150 mA	63	-	250	
		I _C = -500 mA	40	-	-	
h _{FE}	DC current gain	$I_{C} = -150 \text{ mA}; V_{CE} = -2 \text{ V}; \text{ see Fig.2}$				
	BCP51-10; BCP52-10; BCP53-10		63	-	160	
	BCP51-16; BCP52-16; BCP53-16		100	_	250	
V _{CEsat}	collector-emitter saturation voltage	I _C = -500 mA; I _B = -50 mA	_	_	-0.5	V
V _{BE}	base-emitter voltage	$I_{C} = -500 \text{ mA}; V_{CE} = -2 \text{ V}$	_	-	-1	V
f _T	transition frequency	$I_{C} = -10 \text{ mA}; V_{CE} = -5 \text{ V};$ f = 100 MHz	_	115	-	MHz



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PACKAGE OUTLINE



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DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾⁽³⁾	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
11	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

Notes

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- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.
- 3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

DEFINITIONS

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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